PCN# : EPOCP-EX-26-0070-1

Product Change Notice (PCN)

Subject: Addition of Assembly Manufacturing Site
Publication Date: 10/2/2026
Effective Date: 4/1/2027

Revision Description: Initial Release

Description of Change:
Renesas will add an assembly manufacturing site in Japan. In conjunction with this change, the package substrates for RZ/G2L 21 mm package, RZ/G2L 15 mm package, and RZ/G2LC 13 mm package will also be changed. In addition, the tray for the RZ/G2L 15 mm package will be changed as part of this change.

Affected Product List:

RZ/G2L (21mm□PKG)	R9A07G044L14GBG#AC0	R9A07G044L14GBG#BC0
	R9A07G044L18GBG#AC0	R9A07G044L18GBG#BC0
	R9A07G044L24GBG#AC0	R9A07G044L24GBG#BC0
	R9A07G044L28GBG#AC0	R9A07G044L28GBG#BC0
RZ/G2L (15mm□PKG)	R9A07G044L13GBG#AC0	R9A07G044L13GBG#BC0
	R9A07G044L17GBG#AC0	R9A07G044L17GBG#BC0
	R9A07G044L23GBG#AC0	R9A07G044L23GBG#BC0
	R9A07G044L27GBG#AC0	R9A07G044L27GBG#BC0
	R9A07G044L1BGBG#AC0	R9A07G044L1BGBG#BC0
RZ/G2LC (13mm□PKG)	R9A07G044C12GBG#AC0	R9A07G044C12GBG#BC0
	R9A07G044C16GBG#AC0	R9A07G044C16GBG#BC0
	R9A07G044C22GBG#AC0	R9A07G044C22GBG#BC0
	R9A07G044C26GBG#AC0	R9A07G044C26GBG#BC0

Reason for Change:
To enhance supply stability and manufacturing productivity for the RZ product family, an additional assembly manufacturing site will be introduced, and parallel production will begin. In connection with the introduction of the new manufacturing site, the package substrate will also be changed. The additional assembly site will increase manufacturing flexibility and help ensure a stable and reliable supply of products to our customers.

Impact on Fit, Form, Function, Quality & Reliability:
No impact on fit, form, function, quality, or reliability.

Product Identification:
Products can be identified by the country of origin and the SPN shown on the packaging label. Detailed identification information is provided in the appendix. The manufacturing history can also be traced using the trace code marked on the package.

Qualification Completion Date: 12/25/2026

Sample Availability Date: 10/30/2026

Device Material Declaration: Please contact Renesas sales representative.

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact your Renesas sales representative.

Appendix

Comparison Between Current Assembly Site (A) and Additional Assembly Site (B)

(1) Assembly Manufacturing Location

(A) Taiwan (B) Japan

(2) Appearance: The mold compound and marking specifications, including the marking position and font style, may differ between the assembly sites. Therefore, the external appearance of the products may vary slightly.

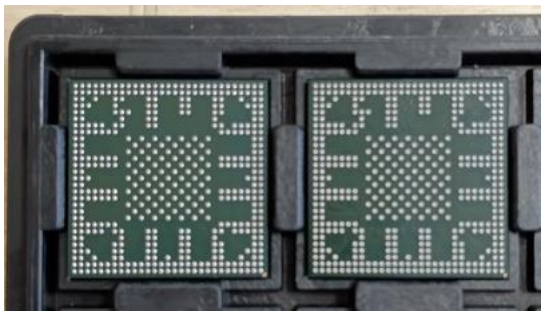
PKG Top view

Site A (Taiwan) **Site B (Japan)**



PKG bottom view

Site A (Taiwan) **Site B (Japan)**



(3) Label Differences

Site A (Taiwan)



Site B (Japan)

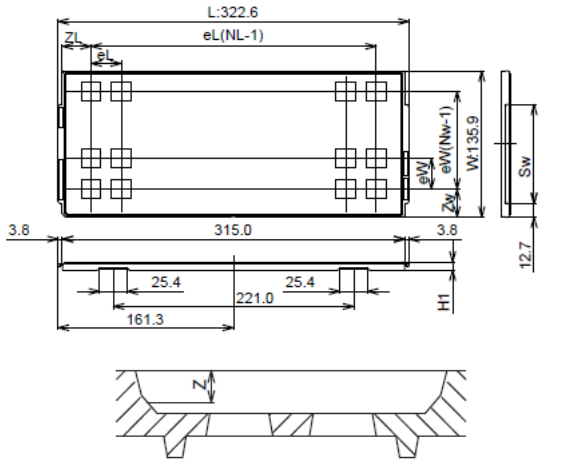


(4) (RZ/G2L 15mm□PKG only)　Change in Tray

Site A (Taiwan)

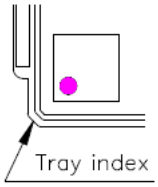
包装仕様 Packing Specification トレイ包装図 TrayOutlineDrawing EA7151508	RDK-H-002371　1/1 ルネサス エレクトロニクス株式会社 Renesas Electronics Corporation

Unit:mm



tray Code		EA7151508
Position dimension of cells	Z	1.56
	Zw	12.90
	ZL	12.70
	eW	18.35
	eL	18.10
	Sw	92.1
Thickness (mm)	H1	7.62
Number of cells	Nw	7
	NL	17
Maximum storage Pcs. IC/Tray		119
Maximum storage Pcs. IC/Inner box		952
Material		Carbon PPE
Heat resistant temperature		135℃MAX
JEDECorCustom		JEDEC
Surface resistance		1.0x10^4≦R＜1.0x10^11Ω

The pin1 is located in the hatching portion.



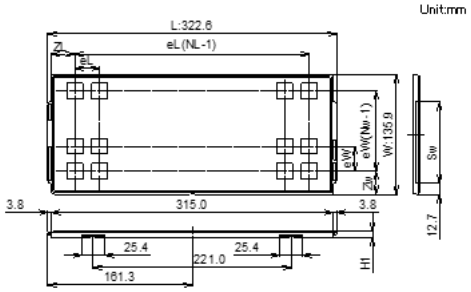
Site B (Japan)

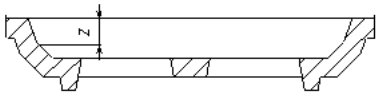
包装仕様 Packing Specification
トレイ包装図 TrayOutlineDrawing
REV.A EA7151536-10

RDK-H-002771 1/1

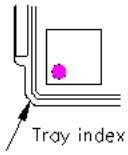
ルネサス エレクトロニクス株式会社
Renesas Electronics Corporation

Unit:mm





The pin1 is located in the hatching portion.



tray Code		REV.A EA7151536-10
Position dimension of cells	Z	1.78
	Zw	12.90
	ZL	12.70
	eW	18.35
	eL	18.10
	Sw	92.10
Thickness (mm)	Hl	7.62
Number of cells	Nw	7
	NL	17
Maximum storage Pcs. IC/Tray		119
Maximum storage Pcs. IC/Inner box		952
Material		PPE
Heat resistant temperature		135℃MAX
JEDECorOustom		JEDEC
Surface resistance		1.0x10^4≦R<1.0x10^11Ω